

From	To	Room/Event	Type
Time		Day 1: Monday - October 27, 2025	
3:00 PM	5:00 PM	Registration Opens - Grand Foyer, Main Level	ASME Meetings
6:30 PM	8:30 PM	Leadership Dinner -By invitation Only	

Time		Day 2: Tuesday - October 28, 2025				
From	To	Room/Event				Type
8:00 AM	8:30 AM	Room: California Ballroom, Main Floor				ASME Meetings
		InterPACK'25 -Opening Remarks by General Chair				
8:30 AM	9:30 AM	Room: California Ballroom, Main Level				Pleanary Session
		Materials Engineering Innovations for Advanced Electronics Cooling By Prof. Ken Goodson				
9:30 AM	11:00 AM	Room: Lassen, 2 nd Floor	Room: Tahoe, 2 nd Floor	Room: Yosemite, 2 nd Floor	Room: Sierra, 2 nd Floor	Technical Sessions
		01-01: Heterogeneous Integration - I	02-01: Single Phase Liquid Cooling - I	03-01: Electronics Packaging- Assembly and Encapsulation	11-01:Advanced Simulation in Science and Engineering - I	
11:00 AM	11:15 AM	Room: Grand Foyer, Main Floor				Break
		Coffee Break				
11:15 AM	12:45 PM	Room: Lassen, 2 nd Floor	Room: Sequoia, 2 nd Floor	Room: Yosemite, 2 nd Floor	Room: The Palm, Main Floor	Technical Sessions
		09-01:Micro/Nano Mechatronics, Microelectronics, Microelectrochemical Systems, and their Applications of Internet of Things - I	02-02: Two Phase Cooling - I	03-02:Electronics Packaing- Power Electronics and Batteries	Data Center Power and Cooling Technologies	Panel
12:45 PM	2:00 PM	Room: Hermosa/Huntington/Manhattan, Main Floor				Lunch Presentations
		LunchAvram Bar-Cohen Award				
2:00 PM	3:30 PM	Room: Laguna, Main Floor		Room: Newport, Main Floor		Tutorials
		Efficient Thermo-Mechanical Simulations Using Compact Models		Center for Energy-Smart Electronic Systems (ES2)		Workshops
3:30 PM	3:45 PM	Room: Grand Foyer, Main Floor				Break
		Coffee Break				
3:45 PM	5:15 PM	Room: Lassen, 2 nd Floor	Room: Tahoe/Redwood, 2 nd Floor	Room: Sequoia, 2 nd Floor	Room: Sierra, 2 nd Floor	Technical Sessions
		06-01: Process Monitoring & Modeling for Additive Electronics	04-01: Power/RF Electronics and Photonics - Emerging Active Cooling & Reliability	03-03: Electronics Packaging - Solders I	Session 05-03: Multiscale Thermal Transport and Energy Storage - III	
5:15 PM	5:45 PM	Room: Lassen, 2 nd Floor				ASME Meetings
		MIPE Meeting				
5:45 PM	7:00 PM	Room: Grand Ballroom, Main Floor				Student Posters
		Interactive Poster Presentations				
7:00 PM	7:45 PM	Room: International Center				ASME Meetings
		EPPD + JEP Meeting (Open)				

Time		Day 3: Wednesday - October 29, 2025				
From	To	Room/Event				Type
8:00 AM	9:30 AM	Room: California Ballroom, Main Level				Plenary Session
		Special Panel on Electronics Packaging and Smart Manufacturing for AI Applications				
9:30 AM	11:00 AM	Room: Lassen, 2 nd Floor	Room: Sequoia, 2 nd Floor	Room: Yosemite, 2 nd Floor	Room: Newport, Main Floor	Technical Sessions
		06-02: Printed Electronics for Defense & Extreme Environments	02-03: Data Centers Metrics and Modeling	03-04: Electronics Packaging - Thermal Management	AI, Investment and Industry Trends	Tutorials
11:00 AM	11:15 AM	Room: Grand Foyer, Main Floor				Break
		Coffee Break				
		Room: Lassen, 2 nd Floor	Room: Tahoe/Redwood, 2 nd Floor	Room: Yosemite, 2 nd Floor	Room: Laguna, Main Floor	Technical Sessions

11:15 AM	12:45 PM	06-03: Advanced Hybrid Electronics Processing & Reliability - I	02-04: Single Phase Liquid Cooling -II	03-05: Electronics Packaging - Solder II	Thermal/Mechanical/Electrical Challenges and Opportunities for Mobile/Wireless/AI/IoT/Automotive and Higher Power Compute Devices	Panel
12:45 PM	2:00 PM	Room: Hermosa/Huntington/Manhattan, Main Floor				Lunch Presentations
		Lunch InterPACK'25 Allan Kraus Award				
2:00 PM	3:30 PM	Room: The Palm, Main Floor		Room: International Center, Main Floor		Workshops
		Special Session: Medium- and Heavy-Duty Hybrid-Electric-Vehicle Drive Technologies		Probabilistic Design for Reliability (PDFr) Concept, and the Roles of Failure Oriented Accelerated Testing (FOAT) and Predictive Analytical ("Mathematical") Modeling		Tutorials
3:30 PM	3:45 PM	Room: Grand Foyer, Main Floor				Break
		Coffee Break				
3:45 PM	5:15 PM	Room: Lassen, 2 nd Floor	Room: Tahoe/Redwood, 2 nd Floor	Room: Yosemite, 2 nd Floor	Room: The Palm, Main Floor	Technical Sessions
		02-05: Two Phase Cooling - II	04-02: Power/RF Electronics and Photonics - Wide Bandgap Semiconductors and Photonics	05-01: Multiscale Thermal Transport and Energy Storage - I	Energy Efficiency and Sustainable Technologies	Tutorials
5:15 PM	6:30 PM	Room: The Palm, Main Floor		Room: Laguna, Main Floor		Tutorials
		K16 Mentoring Program		Machine Learning / Liquid Cooling		Workshops
6:30 PM	7:00 PM	Room: International Center				ASME Meetings
		InterPACK Meeting(Closed)				
7:00 PM	7:30 PM	Room: International Center				ASME Meetings
		InterPACK (Open)				
7:30 PM	8:00 PM	Room: International Center				ASME Meetings
		K-16 Committee Meeting (Open)				

Time		Day 4: Thursday - October 30, 2025				
From	To	Room/Event				Type
8:00 AM	8:45 AM	Room: California Ballroom, Main Floor				Plenary Session
		Unlocking Human Potential through Haptic Sharing By Prof. Yoshihiro Tanaka (Nagoya Institute of Technology)				
8:45 AM	9:30 AM	HAMR Interface Reliability Challenges By Dr. Qing Dai (Western Digital)				
9:30 AM	11:00 AM	Room: Lassen, 2nd Floor	Room: Sequoia, 2 nd Floor	Room: Tahoe/Redwood, 2 nd Floor	Room: Laguna, Main Floor	Technical Sessions
		06-04: Advanced Hybrid Electronics Processing & Reliability - II	05-02: Multiscale Thermal Transport and Energy Storage - II	11-02: Advanced Simulation in Science and Engineering - II	Special Session: NREL Activities and Capabilities in Electronics Packaging Across Multiple Applications	Workshops
11:00 AM	11:15 AM	Room: Grand Foyer				Break
		Coffee Break				
11:15 AM	12:45 PM	Room: Lassen, 2nd Floor	Room: Sequoia, 2 nd Floor	Room: Tahoe/Redwood, 2 nd Floor	Room: The Palm	Technical Sessions
		10-01:Mechatronics, Tribology, and Control of Information Storage Systems and Robotics	01-02: Heterogeneous Integration- II	02-06: Two Phase Cooling - III	Multilayer and Complex Printed Electronics	Panel
12:45 PM	2:00 PM	Room: Hermosa/Huntington/Manhattan, Main Floor				Lunch Presentations
		Lunch InterPACK'25 Awards (Nasser Grayeli Poster, EPPD, JEP)				
2:00 PM	3:30 PM	Room: Laguna, Main Floor		Room: Newport, Main Floor		Workshops
		Mechanics and Thermo-Mechanical Reliability of Advanced Microelectronics Packaging		Additive and Alternative Manufacturing for Electronics		Tutorials
3:30 PM	3:45 PM	Room: Grand Foyer				Break
		Coffee Break				
		Room: Lassen, 2nd Floor	Room: Tahoe/Redwood, 2nd Floor	Room: Yosemite, 2 nd Floor	Room: Laguna, 2 nd Floor	

3:45 PM	5:15 PM	03-06: Electronics Packaging - Substrates, Underfill and TIMs	06-05: Stretchable & Wearable Electronics	09-02: Micro/Nano Mechatronics, Microelectronics, Microelectrochemical Systems, and their Applications of Internet of Things - II	Session 05-04: Multiscale Thermal Transport and Energy Storage - IV	Technical Sessions
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